

**SOLDERING DEVICE AND A METHOD FOR PRODUCING A SOLDER CONNECTION
OF COMPONENTS USING ADHESIVE MATERIAL FOR TEMPORARY CONNECTION
OF THE COMPONENTS**

Abstract

The invention relates to a method for producing a solder connection between a plurality of components (12A, 12B) in a process chamber (74) sealed off from its surroundings by heating and melting solder material (16) which is arranged between the components (12A, 12B) to be connected.

It is proposed that the components (12A, 12B) to be connected are provisionally connected with a bonding material (18) to form a solder group (10) in which the components (12A, 12B) are fixed relative to one another in a joining position.

[Fig.1]